

The Stackup Legend below this is static. If you change the stackup, update the Legend.

| Layer | Material | Thickness | Notes |
|---------------------|----------|-----------|--------------|
| Top Solder Paste | 0.075 | | Solder Paste |
| Top Layer | FR-4 | 1.4 | FR-4 |
| Bottom Layer | FR-4 | 1.4 | FR-4 |
| Bottom Solder Paste | 0.075 | | Solder Paste |

DESIGN INFORMATION
 BOARD SIZE: (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
 - 6900.00 X 6300.00
 Number of Layers: 2
 MIN. TRACK WIDTH: 8 MIL
 MIN. CLEARANCE: 8 MIL
 MIN. VIA PAD SIZE: 24 MIL
 MINIMUM ANNUAL RING 0.15mm (2MIL) EXTERNAL
 PER IPC-D-278 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL HOLES +/- 3 MIL

MATERIAL:
 FR-408 FR-4 High Tg OTHER
THICKNESS: 62 MIL (1.6mm) +/- 10% OTHER
TOLERANCE: ANS IPC-6012 TYPE 3 CLASS 2
 OTHER +/-
BOW & TWIST: ANS IPC-6012 TYPE 3 CLASS 2
 OTHER +/-
COPPER THICKNESS (FINISHED):
 OUTER: 1.4MIL (1oz) 2MIL (1.4oz) 2.8MIL (2oz)
 INNER SIGNAL: 1.4MIL (1oz) 2.8MIL (2oz) N/A

DRILLING:
 REFERENCE: AS SHOWN NC DRILL FILES
 PTH MIN COPPER THICKNESS: 1MIL OTHER
BOARD FINISH:
 SUGSCREEN: TOP BOTTOM
 SUGSCREEN COLOR: WHITE OTHER
 SOLDER RESIST COLOR:
 GREEN BLUE OTHER BLACK

SURFACE FINISH: IMMERSION GOLD (ENIG) ENERP
 MM. TR/SILVER OR EQUIV OTHER

ARRAY/PANEL: CUT AND TRIM PER MESH LAYER 1
 NC ROUTE V. SCORE

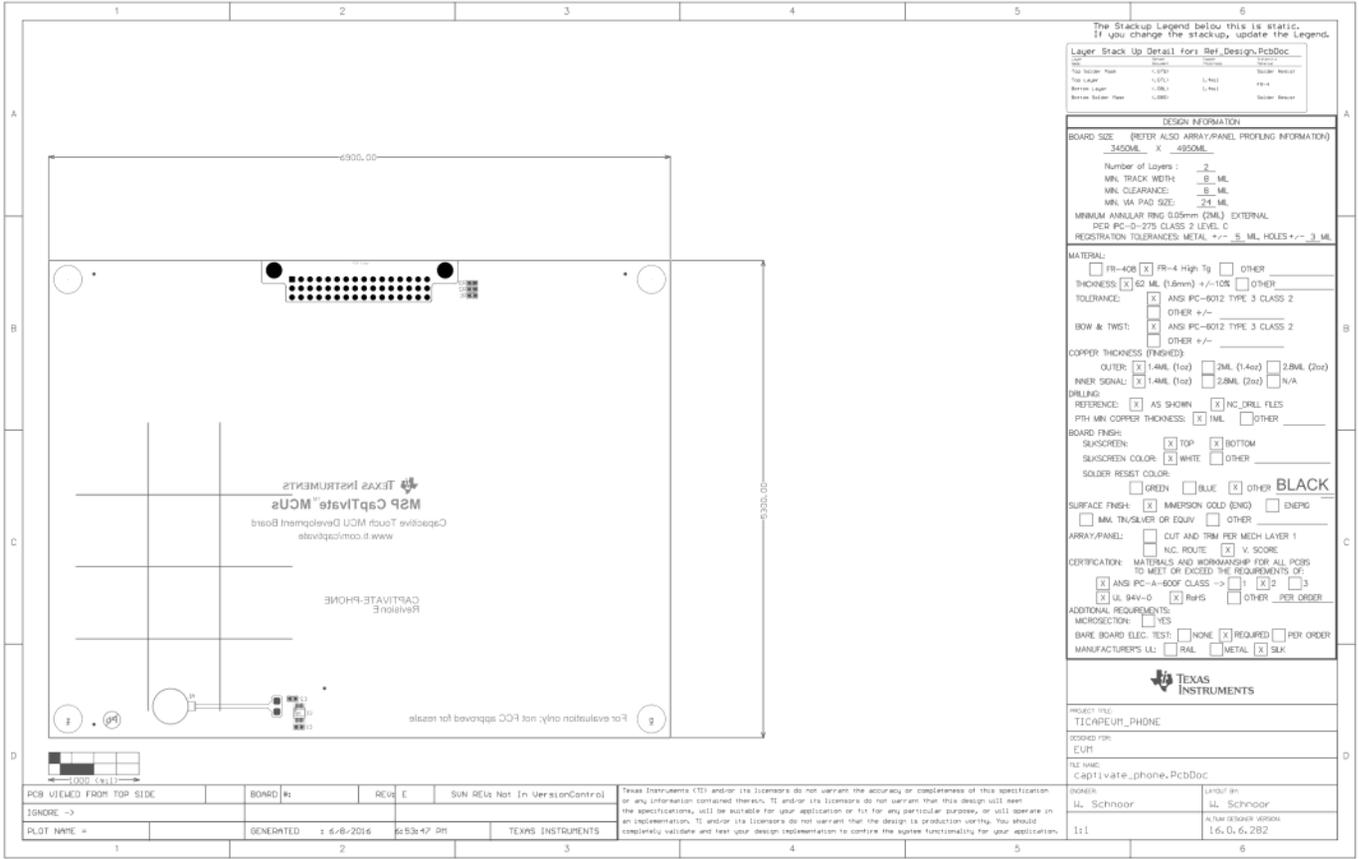
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL POINTS TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANS IPC-A-600F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS:
 MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
 MANUFACTURERS UL: RAL METAL SILK



PROJECT FILE: TIC/PEUP_PHONE
DESIGNED FOR: EUM
FILE NAME: captivate_phone_PcbDoc
DESIGNER: W. Schnoor
DATE: 6/8/2016
DATE PLOTTED: 6/8/2016 4:53:46 PM
PLotted by: W. Schnoor

| | | | | |
|--------------------------|--------------------------------|---|--------------------------------|-------------------|
| PCB VIEWED FROM TOP SIDE | BOARD #: | REV: E | SUN REV: Not in VersionControl | TEXAS INSTRUMENTS |
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| PLLOT NAME = | 1 | 2 | 3 | 4 |



The Stackup Legend below this is static. If you change the stackup, update the Legend.

| Layer | Stack Up Detail | For | Ref. Design | PcbDoc |
|----------------|-----------------|------|-------------|--------|
| Top Layer | 0.035 | FR-4 | 1.40 | 1.40 |
| Prepreg | 0.005 | FR-4 | 1.40 | 1.40 |
| Core | 0.005 | FR-4 | 1.40 | 1.40 |
| Inner Layer | 0.035 | FR-4 | 1.40 | 1.40 |
| Prepreg | 0.005 | FR-4 | 1.40 | 1.40 |
| Core | 0.005 | FR-4 | 1.40 | 1.40 |
| Bottom Layer | 0.035 | FR-4 | 1.40 | 1.40 |
| Prepreg | 0.005 | FR-4 | 1.40 | 1.40 |
| Core | 0.005 | FR-4 | 1.40 | 1.40 |
| Bottom Prepreg | 0.005 | FR-4 | 1.40 | 1.40 |
| Bottom Core | 0.005 | FR-4 | 1.40 | 1.40 |
| Bottom Layer | 0.035 | FR-4 | 1.40 | 1.40 |

DESIGN INFORMATION
 BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
 .3450" X .3450"
 Number of Layers: 2
 MIN. TRACK WIDTH: 8 MIL
 MIN. CLEARANCE: 8 MIL
 MIN. VIA PAD SIZE: 24 MIL
 MINIMUM ANNUAL RING 0.05mm (2MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL HOLES +/- 3 MIL

MATERIAL:
 FR-408 FR-4 High Tg OTHER
 THICKNESS: 62 MIL (1.6mm) +/- 10% OTHER
 TOLERANCE: ANS PC-6012 TYPE 3 CLASS 2
 OTHER +/-
 BOW & TWIST: ANS PC-6012 TYPE 3 CLASS 2
 OTHER +/-
COPPER THICKNESS (FINISHED):
 OUTER: 1.4MIL (Top) 2MIL (1.4oz) 2.8MIL (2oz)
 INNER SIGNAL: 1.4MIL (Top) 2.8MIL (2oz) N/A
DRILLING:
 REFERENCE: AS SHOWN NO DRILL FILES
 PTH MIN COPPER THICKNESS: 1 MIL OTHER
BOARD FINISH:
 SUGSCREEN: TOP BOTTOM
 SUGSCREEN COLOR: WHITE OTHER
 SOLDER RESIST COLOR:
 GREEN BLUE OTHER BLACK
SURFACE FINISH: IMMERSION GOLD (ENIG) ENERP
 MIN. THICKNESS OR EQUIV. OTHER
ARRAY/PANEL: CUT AND TRIM PER MECH LAYER 1
 NO. ROUTE V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL POIS TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANS PC-A-800F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
 MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
 MANUFACTURERS UL: RAL METAL SILK

| | |
|--------------------------|------------------------|
| TEXAS INSTRUMENTS | |
| PROJECT FILE: | TIC/PHONE |
| DESIGNED FOR: | EUM |
| FILE NAME: | capTivate_phone_PcbDoc |
| DESIGNER: | W. Schnoor |
| LAYOUT BY: | W. Schnoor |
| DATE: | 11/16/06 |
| VERSION: | 1.6, 0.6, 2B2 |

| | | | | | |
|--------------------------|------------|------------|-------------|---------------------------------|---|
| PCB VIEWED FROM TOP SIDE | BOARD #: | REV: | E | SUN REV Not [in UserionControl] | Texas Instruments (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to ensure the proper functionality for your application. |
| IGNORE -> | GENERATED: | 11/16/2016 | 16:53:47 PM | TEXAS INSTRUMENTS | |
| PLOT NAME = | | | | | |

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